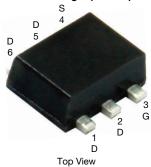


Vishay Siliconix

P-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω) MAX.	I _D (A)	Q _g (TYP.)		
	0.100 at V _{GS} = -4.5 V	-1.44			
-30	0.112 at V _{GS} = -3.7 V	-1.36	8.1 nC		
	0.140 at V _{GS} = -2.5 V	-1.22			

SC-89 Single (6 leads)



Marking Code: C
Ordering Information:

Si1079X-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

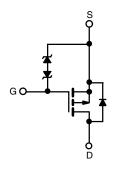
- TrenchFET® power MOSFET
- Typical ESD performance 2500 V
- 100 % R_a tested
- Material categorization:
 For definitions of compliance please see www.vishay.com/doc?99912

Pb-free RoHS

ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- Load switch for portable devices
- Power management



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V_{DS}	-30	V		
Gate-Source Voltage		V_{GS}	± 12			
Continuous Drain Current (T, I = 150 °C)	T _A = 25 °C	_	-1.44 ^{b, c}			
Continuous Drain Current (1) = 150 C)	T _A = 70 °C	I _D	-1.15 ^{b, c}			
Pulsed Drain Current (t = 300 μs)		I _{DM}	-8	A		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	-0.28 ^{b, c}			
Maximum Dower Dissination	T _A = 25 °C	D-	0.33 b, c	W		
Maximum Power Dissipation	T _A = 70 °C	- P _D	0.21 ^{b, c}	VV		
Operating Junction and Storage Temperature Rang	e	T _J , T _{stg}	-55 to 150	°C		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum Junction-to-Ambient ^{a, b}	t ≤ 5 s	R_{thJA}	300	375	°C/W	
Wiaximum Junction-to-Ambient -, -	Steady State		360	450		

Notes

- a. Maximum under steady state conditions is 450 °C/W.
- b. Surface mounted on 1" x 1" FR4 board.
- $c. \ t=5 \ s.$



www.vishay.com

Vishay Siliconix

SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static				l .		,	
Drain-Source Breakdown Voltage	V_{DS}	V _{GS} = 0 V, I _D = -250 μA	-30	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 A	-	-21	-	mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = -250 μA	-	3	-		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	-0.6	-	-1.5	V	
0.1. 0		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$	-	-	± 10	μΑ	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$	-	-	± 1		
Zana Onto Wallana Burin O annal		V _{DS} = -30 V, V _{GS} = 0 V	-	-	-1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -30 V, V _{GS} = 0 V, T _J = 85 °C	-	-	-10	1	
On-State Drain Current a	I _{D(on)}	$V_{DS} = \ge -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	-8	-	-	Α	
	· ·	$V_{GS} = -4.5 \text{ V}, I_D = -1.4 \text{ A}$	-	0.083	0.100	Ω	
Drain-Source On-State Resistance a	R _{DS(on)}	$V_{GS} = -3.7 \text{ V}, I_D = -1.3 \text{ A}$	-	0.093	0.112		
	, ,	V _{GS} = -2.5 V, I _D = -0.7 A	-	0.108	0.140		
Forward Transconductance	9 _{fs}	V _{DS} = -15 V, I _D = -1.4 A	-	10	-	S	
Dynamic b							
Input Capacitance	C _{iss}		-	750	-		
Output Capacitance	C _{oss}	V _{DS} = -15 V, V _{GS} = 0 V, f = 1 MHz	-	67	-	pF	
Reverse Transfer Capacitance	C _{rss}		-	60	-		
	Q_g	V _{DS} = -15 V, V _{GS} = -10 V, I _D = -1.4 A	-	17	26		
Total Gate Charge			-	8.1	13	1 ,	
Gate-Source Charge	Q_{gs} $V_{DS} = -15 V, V_{GS} =$		-	1.2	-	nC	
Gate-Drain Charge	Q _{gd}		-	2.2	-		
Gate Resistance	R _g	f = 1 MHz	3.6	18	36	Ω	
Turn-On Delay Time	t _{d(on)}		-	22	33		
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_1 = 13 \Omega$	-	33	50		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong -1.15$ A, $V_{GEN} = -4.5$ V, $R_g = 1$ Ω	-	58	87		
Fall Time	t _f		-	30	45		
Turn-On Delay Time	t _{d(on)}		-	5	10	ns -	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_L = 13 \Omega$	-	20	30		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong -1.15 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$	-	80	120		
Fall Time	t _f		-	30	45		
Drain-Source Body Diode Characteristics							
Pulse Diode Forward Current ^a	I _{SM}		-	-	-8	Α	
Body Diode Voltage	V _{SD}	I _S = -1.15 A	-	-0.75	-1.2	V	
Body Diode Reverse Recovery Time	t _{rr}		-	16	24	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 4 45 6 31/11 400 4/	-	7	14	nC	
Reverse Recovery Fall Time	ta	I _F = -1.15 A, dl/dt = 100 A/μs	-	9	-		
Reverse Recovery Rise Time	t _b		-	7	-	ns	

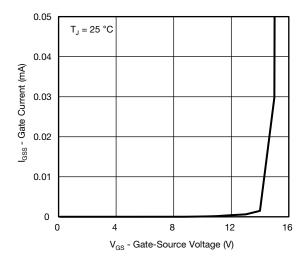
Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

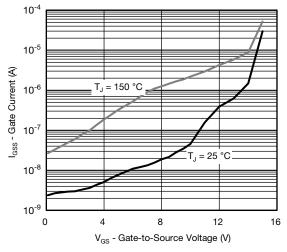
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



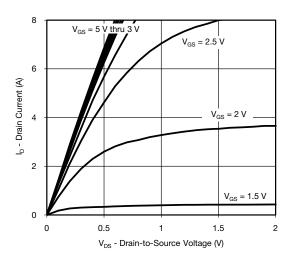
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



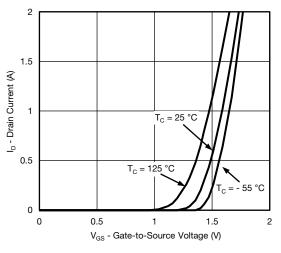
Gate Current vs. Gate-Source Voltage



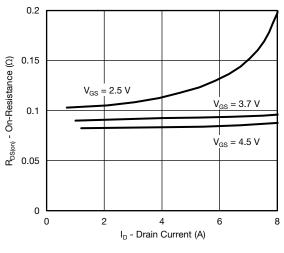
Gate Current vs. Gate-to-Source Voltage



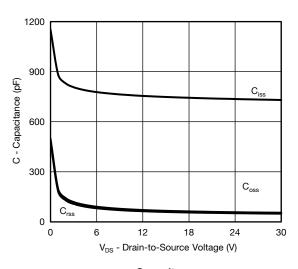
Output Characteristics



Transfer Characteristics Curves vs. Temperature



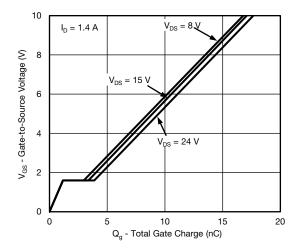
On-Resistance vs. Drain Current



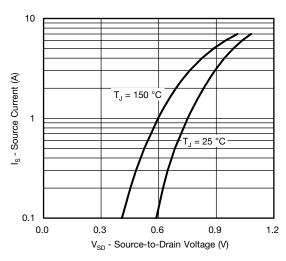
Capacitance



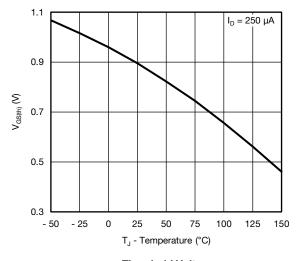
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



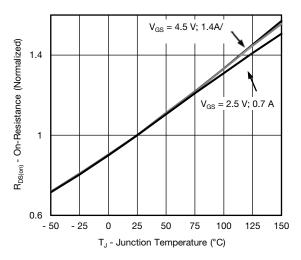
Gate Charge



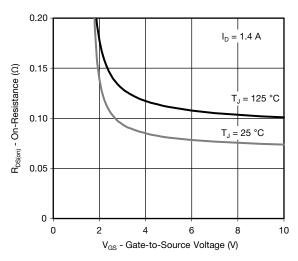
Source-Drain Diode Forward Voltage



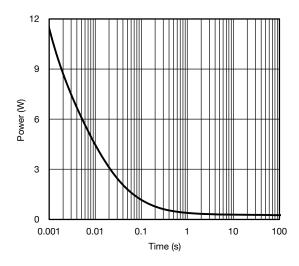
Threshold Voltage



On-Resistance vs. Junction Temperature



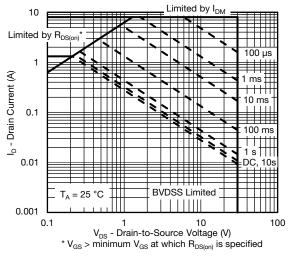
On-Resistance vs. Gate-to-Source Voltage

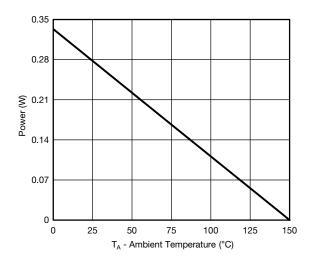


Single Pulse Power, Junction-to-Ambient



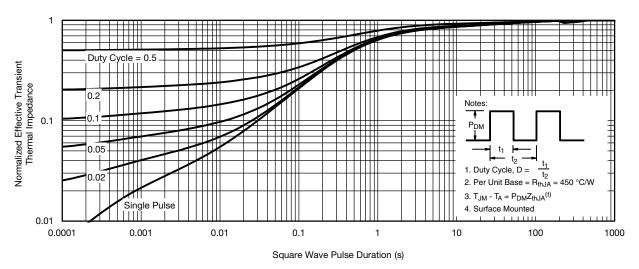
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)





Safe Operating Area, Junction-to-Ambient

Power Junction-to-Ambient

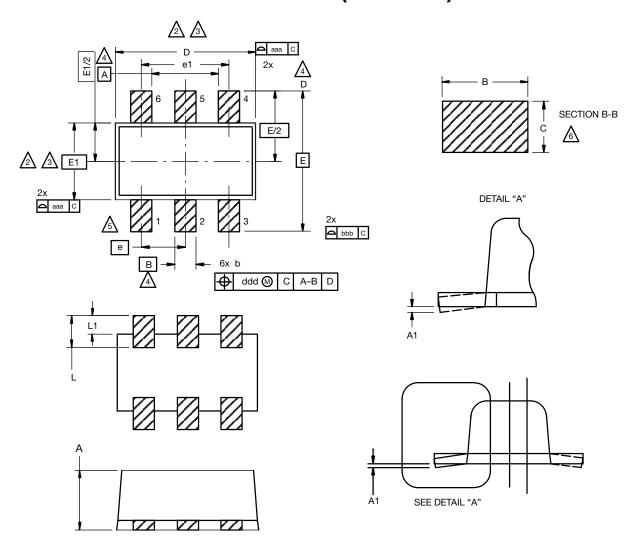


Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?62966.



SC-89 6-Leads (SOT-563F)



Notes

1. Dimensions in millimeters.

Dimension D does not include mold flash, protrusions or gate burrs. Mold flush, protrusions or gate burrs shall not exceed 0.15 mm per dimension E1 does not include interlead flash or protrusion, interlead flash or protrusion shall not exceed 0.15 mm per side.

Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, the bar burrs, gate burrs and interlead flash, but including any mismatch between the top and the bottom of the plastic body.

ADatums A, B and D to be determined 0.10 mm from the lead tip.

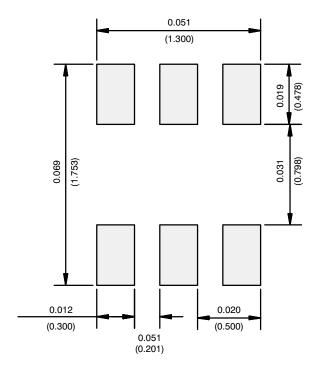
A Terminal numbers are shown for reference only.

These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIM.	MILLIMETERS					
	MIN.	NOM.	MAX.			
Α	0.56	0.58	0.60			
A1	0	0.02	0.10			
b	0.15	0.22	0.30			
С	0.10	0.14	0.18			
D	1.50	1.60	1.70			
E	1.50	1.60	1.70			
E1	1.15	1.20	1.25			
е	0.45	0.50	0.55			
e1	0.95	1.00	1.05			
L	0.25	0.35	0.50			
L1	0.10	0.20	0.30			
C14-0439-Rev. C, 11-Aug-14 DWG: 5880						



RECOMMENDED MINIMUM PADS FOR SC-89: 6-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

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Revision: 02-Oct-12 Document Number: 91000

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